

Title (en)

Method for manufacturing a body-worn electronic device adapted to the shape of an individual's body area

Title (de)

Verfahren zur Herstellung eines am Körper zu tragenden elektronischen Gerätes, welches an den Form eines Körperteils eines Individuum angepasst ist.

Title (fr)

Procédé de fabrication d'un dispositif électronique portable, adapté à la forme d'une partie du corps d'un individu

Publication

**EP 1345470 A2 20030917 (EN)**

Application

**EP 03007673 A 20030403**

Priority

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Abstract (en)

A body-worn device is manufactured by preparing a digitised three-dimensional representation (1) of an individual's body area whereat the body-worn device shall be applied. From such digitised three-dimensional representation there are automatically determined (20) characteristic features of the individual's area as digitised. In dependency from such determining (20), the digitised representation (1) is amended in a detailing step (22). The result is a digitised representation. This detailed digitised representation controls the shell manufacturing process (36) the resulting shell of which being assembled (38) to the body-worn device. <IMAGE>A body-worn device is manufactured by preparing a digitised three-dimensional representation (1) of an individual's body area whereat the body-worn device shall be applied. From such digitised three-dimensional representation there are automatically determined (20) characteristic features of the individual's area as digitised. In dependency from such determining (20), the digitised representation (1) is amended in a detailing step (22). The result is a digitised representation. This detailed digitised representation controls the shell manufacturing process (36) the resulting shell of which being assembled (38) to the body-worn device. <IMAGE>

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CPC (source: EP US)

**H04R 25/652** (2013.01 - EP US); **H04R 25/658** (2013.01 - EP US)

Cited by

US7605812B2; EP1858293A1; EP1939776A3; EP2249271A1; EP1558058A3; EP1675430A1; EP1909537A3; CN106941653A; EP2068282A3; EP3879852A1; CN113039814A; US8090127B2; US7447556B2; US8616214B2; US8150542B2; WO2007059633A1; WO2004105432A3; WO2006117409A3; WO2011044903A3; WO2013149645A1; EP1909537A2; US7949145B2; US8068653B2; EP2068282A2; US7606381B2; US7308328B2; US11481530B2; US11893324B2

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